BROADCOM

PCN-304925

Product Change Notice

Issue Date: 16-April-2026

Change Description:
Add new substrate supplier

Parts Affected:
BCM89881B1BFBG
BCM89883B1BFBG

Description and Extent of Change:
Add new supplier for package substrate - TCI. There is no change to the substrate design or construction (see table below):

Items from the CDCQ	Existing Supplier (UMTC)	New Supplier (TCI)
a. Substrate material (e.g., FR5, BT, etc.):	Laminate	Laminate
b. Substrate thickness (mm):	0.36	0.36
c. Number of substrate metal layers:	4	4
d. Plating composition of ball solderable surface:	Electrolytic Ni/Au	Electrolytic Ni/Au
e. Panel singulation method:	Saw	Saw
f. Solder ball composition:	96.5Sn/3.0Ag/0.5Cu	96.5Sn/3.0Ag/0.5Cu
g: Solder ball diameter (mils):	19.69mils (0.5mm)	19.69mils (0.5mm)

Reasons for Change:
Existing substrate supplier (UMTC) is obsoleting the substate.

Effect of Change on Fit, Form, Function, Quality, or Reliability:
The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification has been performed on representative products to ensure normal parametric distribution, consistent electrical performance, and reliability.

Effective Date of Change:
Product shipments using this change will begin after **31-December-2026**. Timing of shipment of the changed part will vary by part number depending on qualification completion, customer demand, and inventory levels.

Sample Availability:
Samples with the updated substrate will be available after **31-August-2026**. Please contact your Broadcom Sales Representative by **30-July-2026** to reserve your samples.

Qualification Data:

Qualification Data on an 8x8mm package with TCI substrate will be available in **October 2026**. Please reference the qualification plan below.

Test	AEC#	Method	Condition	Sample Size	Duration	Result
PC/MSL	A1	JESD22-A113, J-STD-020	Level 3 (soak: 30°C, 60%RH); Peak Reflow Temp = 260°C.	All units for bHAST, uHAST, TC, PTC	192 hrs	Pending
bHAST	A2	JESD22-A110	Pre-con Parts; 110°C, 85%RH.	3 lots * 77 units/lot = 231 units	264 hrs	Pending
uHAST	A3	JESD22-A118	Pre-con Parts; 130°C, 85%RH.	3 lots * 77 units/lot = 231 units	96 hrs	Pending
TC	A4	JESD22-A104	Pre-con Parts; air to air; -55°C to 125°C.	3 lots * 77 units/lot = 231 units	1000 cys	Pending
HTSL	A6	JESD22-A103	Ta = +150°C	1 lot * 45 units	500 hrs	Pending
HTOL	B1	JESD22-A108	Ta = 125°C, >80% Node Toggle; VDD=1.1*VDDnom.	3 lot * 77 units	1000 hrs	Pending
WBS	C1	AEC-Q100-001	Cpk > 1.67	1 lot * 5 units (30 bonds/each)	-	Pending
WBP	C2	MIL-STD-883, Method 2011, Cond. C or D	Cpk > 1.67	1 lot * 5 units (30 bonds/each)	-	Pending
SBS	C5	AEC-Q100-010	Cpk > 1.67	3 lots * 10 units/lot = 30 units (5 balls/each)	-	Pending

Software / Firmware Update:

This change does not impact Software / Firmware.

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice **within 30 days of delivery**. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.